

Errata for OPAx344, OPAx345 Data Sheet Literature Number SBOS107 (Revision A)

The OPA344, OPA2344, OPA4344, OPA345, OPA2345, and OPA4345 devices conform functionally to the product data sheet (SBOS107A), except for the anomaly described below.

Errata Index:

1. Figure correction.

1 Erratum #1: Figure Correction

Brief Description

The temperature values shown in the Typical Performance Curves graph for *Output Voltage Swing vs Output Current* (Figure 14, not numbered) are incorrect.

Detailed Description

As printed in the published product data sheet (literature number [SBOS107A](#)), the -40°C and 85°C temperature values shown in the 14th Typical Performance Curves graph (page 7) are reversed. The graph in [Figure 1](#) shows the corrected temperature values.

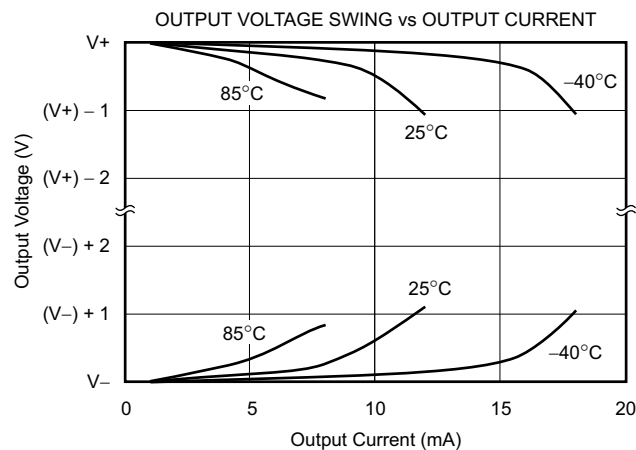


Figure 1. Corrected Typical Performance Curve

Impact to Customer

The -40°C and $+85^{\circ}\text{C}$ temperature labels are now correctly associated with their corresponding curve, which reflects the true output behavior of the CMOS output stage. Most customer applications employing this operational amplifier family have load currents that coincide with the typical $10\text{-k}\Omega$ load used in the Electrical Characteristics table. Currents at that level fall in the region of the graph where temperature has little influence on the output voltage versus output current performance. The correct output voltage behavior at higher load currents versus temperature can now be obtained from the graph.

SW or HW Workaround

No workaround is required.

Affected Devices

OPA344, OPA2344, OPA4344, OPA345, OPA2345, and OPA4345 operational amplifiers.

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